3.2X1.6mm SMD CHIP LED LAMP

Part Number: KPC-3216ZGC-E Green

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- 3.2X1.6mm SMT LED, 1.1mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

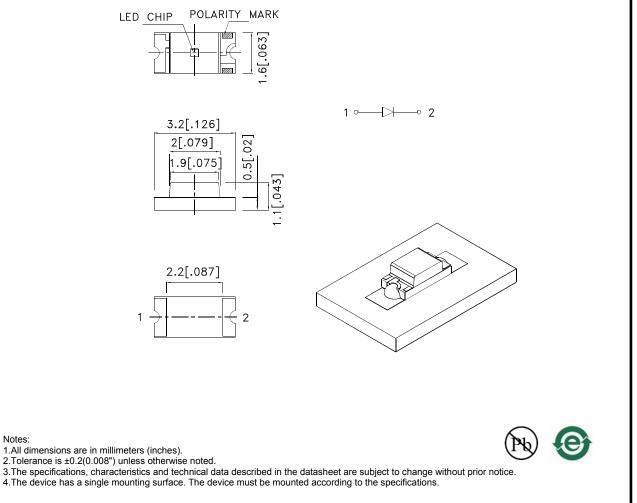
The Green source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



SPEC NO: DSAK3304 **APPROVED: WYNEC**

Notes:

REV NO: V.1 CHECKED: Allen Liu DATE: JAN/08/2010 DRAWN: F.F.Zhou

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Selection Guide									
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]				
			Min.	Тур.	201/2				
KPC-3216ZGC-E	Green (InGaN)	WATER CLEAR	280	650	120°				

Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

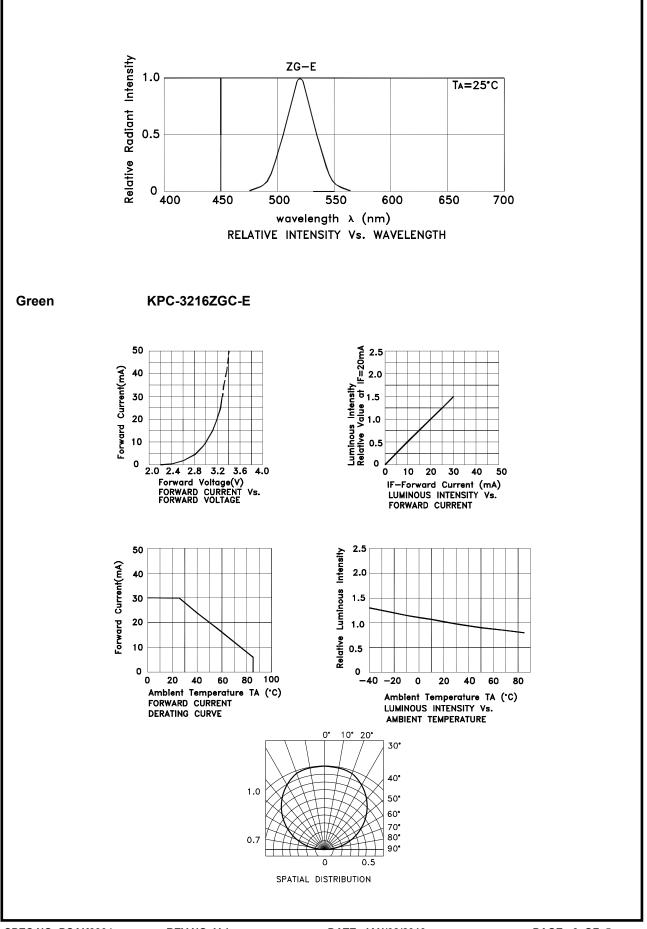
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	525		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	35		nm	I⊧=20mA
С	Capacitance	Green	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.2	4	V	IF=20mA
IR	Reverse Current	Green		50	uA	VR=5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

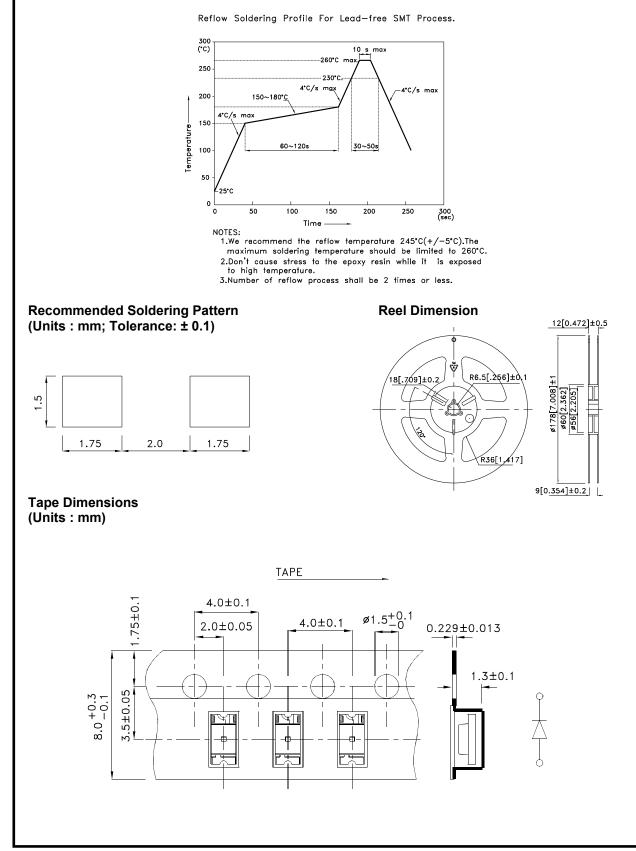
Parameter	Green	Units		
Power dissipation	120	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	100	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KPC-3216ZGC-E

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.



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